



Sir:



09/25/00

Transmitted herewith for filing is the Patent Application of:

Inventor: HORNG-WEN CHEN AND CHI-HOW WU

For: AN IN-SITU STRIP PROCESS FOR POLYSILICON ETCHING IN DEEP SUB-MICRON TECHNOLOGY

Enclosed are:

- ☒ 6 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to Taiwan Semiconductor Manufacturing Company
- ☐ An associate power of attorney

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 690.
TOTAL CLAIMS	20 -20=	0	x 18 =	\$ 0.
INDEP CLAIMS	3 -3=	0	x 78 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
			SUB TOTAL	\$ 690.
			ASSIGNMENT	\$40.
			TOTAL	\$ 730.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 730. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
 - ☒ Any additional filing fees required under 37 CFR \$1.16.
 - ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

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